TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Joinder to Security Agreement

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
R & D Circuits		09/22/2011	CORPORATION: NEW JERSEY
R&D Circuits Holdings LLC		09/22/2011	LIMITED LIABILITY COMPANY: DELAWARE
R&D Sockets, Inc.		09/22/2011	CORPORATION: DELAWARE

RECEIVING PARTY DATA

Name:	Patriot Capital II, L.P.
Street Address:	509 South Exeter Street
Internal Address:	Suite 210
City:	Baltimore
State/Country:	MARYLAND
Postal Code:	21202
Entity Type:	LIMITED PARTNERSHIP: DELAWARE

PROPERTY NUMBERS Total: 1

Property Type	Number	Word Mark
Serial Number:	75364003	GRYPHICS

OP $40.00 75364003

CORRESPONDENCE DATA

Fax Number: (312)698-4533
Phone: 312.750.3617
Email: bbylica@mcguirewoods.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: Bryan P. Bylica, McGuireWoods LLP
Address Line 1: 77 West Wacker Drive
Address Line 2: Suite 4100
Address Line 4: Chicago, ILLINOIS 60601-1818

ATTORNEY DOCKET NUMBER:	2056050-0004

NAME OF SUBMITTER:	Bryan P. Bylica
Signature:	/s/ Bryan P. Bylica
Date:	09/28/2011

Total Attachments: 12
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JOINDER TO
PATENTS, TRADEMARKS, COPYRIGHTS AND LICENSES SECURITY AGREEMENT

This JOINDER AGREEMENT (this ***"Joinder"***) dated as of September 22, 2011, is executed by the undersigned for the benefit of Patriot Capital II, L.P., a Delaware limited partnership (***"Patriot"***), in connection with that certain Patents, Trademarks, Copyrights and Licenses Security Agreement dated as of April 29, 2011, among R & D Circuits, a New Jersey corporation, R&D Circuits Holdings LLC, a Delaware limited liability company and Patriot (as amended, restated, supplemented, or otherwise modified from time to time, the ***"Security Agreement"***) for the purpose of joining R&D Sockets, Inc., a Delaware corporation (***"Sockets"***) as an additional "Assignor" thereunder. Capitalized terms not otherwise defined herein are being used herein as defined in the Security Agreement.

In order to join Sockets as an Assignor the Security Agreement, each party signatory hereto is required to execute this Joinder pursuant to the Security Agreement.

In consideration of the premises and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each signatory hereby agrees as follows:

1. Sockets assumes all the obligations of an Assignor under the Security Agreement and agrees that it is an Assignor and bound as an Assignor under the terms of the Security Agreement, as if it had been an original signatory to such agreement. In furtherance of the foregoing, Sockets hereby grants to Patriot a continuing security interest in all of its right, title, and interest in, to and under the Collateral owned thereby, whether presently existing or hereafter created or acquired.

2. The exhibits to the Security Agreement are hereby amended to add the information relating to Sockets set out on the exhibits hereto. Effective as of the date hereof, each Assignor party hereto makes to Patriot the representations and warranties set forth in the Security Agreement applicable to such party and the applicable Collateral and confirms that such representations and warranties are true and correct after giving effect to such amendment to such exhibits.

3. This Joinder shall be deemed to be part of, and a modification to, the Security Agreement and shall be governed by all the terms and provisions of the Security Agreement, with respect to the modifications intended to be made to such agreement, which terms are incorporated herein by reference, are ratified and confirmed and shall continue in full force and effect as valid and binding agreements of each such person or entity enforceable against such person or entity. Each such party hereby waives notice of Patriot's acceptance of this Agreement.

4. Each such party will deliver an executed original of this Joinder to Patriot and agrees that this Agreement may be filed with the United States Patent and Trademark Office and the United States Copyright Office, as applicable.

[SIGNATURE PAGE FOLLOWS]

Each of the undersigned has caused this Joinder Agreement to be duly executed and delivered as of the date first above written.

R & D CIRCUITS,
a New Jersey corporation

By: _____
Name: James Russell
Title: Chief Executive Officer

R&D CIRCUITS HOLDINGS LLC,
a Delaware limited liability company

By: _____
Name: James Russell
Title: Chief Executive Officer

R&D SOCKETS, INC.,
a Delaware corporation

By: _____
Name: James Russell
Title: Chief Executive Officer

Acknowledged:

PATRIOT CAPITAL II, L.P.,
a Delaware limited partnership

By: PATRIOT PARTNERS II, LLC,
a Delaware limited liability company
Its: General Partner

By: _____
Name: Charles P. McCusker, Jr.
Title: Managing Member

Each of the undersigned has caused this Joinder Agreement to be duly executed and delivered as of the date first above written.

R & D CIRCUITS,
a New Jersey corporation

By: _____
Name: James Russell
Title: Chief Executive Officer

R&D CIRCUITS HOLDINGS LLC,
a Delaware limited liability company

By: _____
Name: James Russell
Title: Chief Executive Officer

R&D SOCKETS, INC.,
a Delaware corporation

By: _____
Name: James Russell
Title: Chief Executive Officer

Acknowledged:

NOTE PURCHASER:

PATRIOT CAPITAL II, L.P.,
a Delaware limited partnership

By: PATRIOT PARTNERS II, LLC,
a Delaware limited liability company
Its: General Partner

By: _____
Name: Charles P. McCusker, Jr.
Title: Managing Member

EXHIBIT A

R & D Circuits Intellectual Property

U.S. PATENTS AND PATENT APPLICATIONS		
Title	**Application/Patent Number (Filed/Issued)**	**Status**
Apparatus and Method for a Conductive Elastomer on a Coaxial Cable or a Microcable to Improve Signal Integrity Probing	61/459,239	Pending
Electrical Connector for Connecting an Adaptor Board or Electrical Component to a Main Printed Circuit Board	61/340,277	Expired
Electrical Connector for Connecting an Adaptor Board or Electrical Component to a Main Printed Circuit Board	61/340,519 (3/18/2010)	Expired
Electrical Connector for Connecting an Adaptor Board or Electrical Component to a Main Printed Circuit Board	13/065,006 (3/11/2011)	Pending
Embedded Circuits in Interposer Board for Improving Power Distribution and Power Dissipation in Interconnect Configuration	61/276,661 (9/15/2009)	Expired
Embedded Components in Interposer Board for Improving Power Gain (Distribution) and power loss (Dissipation) in interconnect configuration	12/655,834 (1/8/2010)	Pending
Laser Skived Solder Dam	61/284,979 (12/30/2009)	Expired
Method and Apparatus for Scoring or Skiving a Solder Dam	12/798,216 (3/31/2010)	Pending
Method and Apparatus for Improving Power Distribution and Dissipation for Interconnect Configurations	61/215,369 (5/4/2009)	Expired

Method and Apparatus for Improving Power Gain and Loss for Interconnect Configurations	12/655,858 (1/8/2010)	Pending
Method and Structure for Coaxial Via Routing in Printed Circuit Boards for Improved Signal Integrity	61/338,918 (2/25/2010)	Expired
Method and Structure for Coaxial via Routing in Printed Circuit Boards for Improved Signal Integrity	12/798,217 (3/31/2010)	Pending
Method and Structure for Directly Connecting Coaxial or Micro Coaxial Cables, et al.	61/397,170 (6/10/2010)	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	61/008,262 (12/18/2007)	Expired
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	61/009,272 (12/27/2007)	Expired
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	7,766,667 (8/3/2010)	Issued
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	12/799,712 (4/30/2010)	Pending
Method for Reducing Contact Resistance in Interconnect Medium	61/456,299 (11/4/2010)	Pending (Non-provisional being prepared)
Embedded Isolation Filter	61/404,521 (10/5/2010)	Pending (Non-provisional being prepared)
Looped Wire Elastomeric Contactor	61/401,027 (8/6/2010)	Pending (Non-provisional being prepared)

FOREIGN PATENTS AND PATENT APPLICATIONS		
Title	**Application/Patent Number (Filed/Issued)**	**Status**
Embedded Components in Interposer Board for Improving Power Gain (Distribution) and power loss (Dissipation) in interconnect configuration	PCT/US2010/00049 (1/8/2010)	Pending
Embedded Components in Interposer Board for Improving Power Gain (Distribution) and power loss (Dissipation) in interconnect configuration	Taiwan 99128788	Pending
Method and Apparatus for Improving Power Gain and Loss for Interconnect Configurations	PCT/US/2010/00043 (1/8/2010)	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	PCT/US2008/013842 (12/17/2008)	Expired
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	Korea 10-2010-7015693 (7/15/2010)	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	Japan 2010539485 (6/18/2010)	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	Singapore 201003949-3	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	Taiwan 097149346	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	China 200880121549.9	Pending
Separable Electrical Connectors Using Isotropic Conductive Elastomer Interconnect Medium	Europe 08863567.7 (6/16/2010)	Pending

PATENTS – UNITED STATES

Title	Application Number	Patent Number	Status
ELECTRICAL CONNECTOR WITH MULTIPLE MODES OF COMPLIANCE	08/852,116	5,938,451	Granted
REPLACEABLE CHIP MODULE	08/955,563	5,913,687	Granted
MULTI-MODE COMPLIANCE CONNECTOR AND REPLACEABLE CHIP MODULE UTILIZING THE SAME	09/182,164	6,247,938	Granted
REPLACEABLE CHIP MODULE	09/304,707	6,178,629	Granted
ELECTRICAL CONNECTOR WITH MULTIPLE MODES OF COMPLIANCE	09/305,165	6,135,783	Granted
MULTI-MODE COMPLIANT CONNECTOR AND REPLACEABLE CHIP MODULE UTILIZING THE SAME	09/426,958	6,409,521	Granted
ELECTRICAL CONNECTOR WITH MULTIPLE MODES OF COMPLIANCE	09/551,518	6,231,353	Granted
CONTROLLED COMPLIANCE FINE PITCH INTERCONNECT	10/031,422	6,830,460	Granted
FLEXIBLE COMPLIANT INTERCONNECT	10/169,431	6,939,143	Granted
COMPLIANT INTERCONNECT ASSEMBLY	10/453,322	6,957,963	Granted
COMPLIANT INTERCONNECT ASSEMBLY	10/992,170	7,114,960	Granted
CONTROLLED COMPLIANCE FINE PITCH ELECTRICAL INTERCONNECT	10/992,482	7,160,119	Granted
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	11/030,213	7,326,064	Granted
COMPLIANT INTERCONNECT ASSEMBLY	11/130,494	7,121,839	Granted
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	11/253,510	7,297,003	Granted
NORMALLY CLOSED ZERO INSERTION FORCE CONNECTOR	11/325,127	7,214,069	Granted
METHOD OF MAKING A COMPLIANT INTERCONNECT ASSEMBLY	11/369,781	7,900,347	Granted
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	11/935,084	7,422,439	Granted
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	12/060,586	7,537,461	Granted
A SOCKET WITH A HOUSING WITH CONTACTS WITH BEAMS OF UNEQUAL LENGTHS	12/640,863	7,857,631	Granted
COMPOSITE CONTACT FOR FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	12/293,499		Filed
COMPOSITE CONTACT FOR FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY			Unfiled

PATENTS – FOREIGN

Title	Application Number	Patent Number	Status	Country
CONTROLLED COMPLIANCE FINE PITCH INTERCONNECT	955283.7		Filed	European Patent Convention
FLEXIBLE COMPLIANT INTERCONNECT	1904826.3		Filed	European Patent Convention
ELECTRICAL INTERCONNECT ASSEMBLY WITH INTERLOCKING CONTACT SYSTEM	4757059.3		Filed	European Patent Convention
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	8744848.6		Filed	European Patent Convention
COMPOSITE CONTACT FOR FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	11 2007 000 677.3		Filed	Germany
COMPOSITE CONTACT FOR FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	2009-501680		Filed	Japan
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	2010-502240		Filed	Japan
LOW INSERTION FORCE BGA SOCKET ASSEMBLY	To be assigned, based on PCT/US2009 / 069647		Filed	Japan
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	8103032.6		Filed	Hong Kong
MULTI-MODE COMPLIANT CONNECTOR AND REPLACEABLE CHIP MODULE UTILIZING THE SAME	10-1999-7010151	509967	Granted	Republic of Korea
ELECTRICAL INTERCONNECT ASSEMBLY WITH INTERLOCKING CONTACT SYSTEM	10-2006-7000789		Filed	Republic of Korea

FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	10-2007-7013422		Filed	Republic of Korea
COMPOSITE CONTACT FOR FINE PITCH ELECTRICAL ASSEMBLY	10-2008-7023049		Filed	Republic of Korea
FINE PITCH ELECTRICAL INTERCONNECT ASSEMBLY	10-2009-7022600		Filed	Republic of Korea
LOW INSERTION FORCE BGA SOCKET ASSEMBLY	10-2011-7017191		Filed	Republic of Korea

EXHIBIT B

TRADEMARKS		
Mark	**Application/Registration Number (Filed/Registered)**	**Status**
ELASTCONNECT	85/176,668 (11/15/2010)	Pending
ELASTECH	85/176,703 (11/15/2010)	Pending
VIA ANYWHERE	85/200,613 (12/17/2010)	Pending
CONNECTFLEX	85/179,965 (11/18/2010)	Pending – To be Abandoned
EC TECHNOLOGY	85/105,352 (8/11/2010)	Pending – To be Abandoned
KGLB	3,944,000 (4/12/2011) 85/105,102 (08/11/2010)	Registered (Principal)
MOTHER-DAUGHTER TECHNOLOGY	76/675,316 (4/10/2007)	Abandoned
KNOWN GOOD BOARD	3,906,040 (1/11/2011)	Registered (Supplemental)
KNOWN GOOD LOAD BOARD	3,909,579 (01/18/2011) 85/104,872 (8/11/2010)	Registered
SPACE TRANSFORMER TECHNOLOGY	76/675,315 (4/10/2007)	Abandoned
TECHNOLOGY SOLUTIONS ACROSS THE BOARD	85/106,196 (8/12/2010)	Pending – To be Abandoned
QUALITY ACROSS THE BOARD	3,827,708 (8/3/2010) 77/899,161 (12/22/2009)	Registered (Principal)

Country Name	Application Number	Registration Number	Registration Date	Status Description	Class Number	MARK
United States	75/364,003	2,208,761	08-Dec-98	Registered	9	GRYPHICS

EXHIBIT C

COPYRIGHTS
NONE

EXHIBIT D

1. Purchase Agreement, by and between Intel Corporation and R & D Cricuits dated February 8, 2011.

2. Purchasing Order, by and between Ansys, Inc. and R & D Circuits, dated September 30, 2010.

3. Maintenance Service Agreement, by and between Orbotech, Inc. and R & D Circuits, dated December 16, 2010, together with Purchase Order dated December 17, 2010.

4. Maintenance Service Agreement, by and between Orbotech, Inc. and R & D Circuits, dated December 20, 2010, together with Purchase Order dated January 25, 2011.

5. Software License and Maintenance Agreement, by and between Cadence Design Systems, Inc. and R & D Circuits, dated November 7, 2008, together with Software Support Quotation, dated March 9, 2011.

6. Non-Exclusive License Agreement, dated September 24, 2010, between Paricon Technologies Corporation and R & D Circuits.

7. Purchasing Order, by and between Aegis Software and R & D Circuits, dated March 30, 2011.

8. Licensing Agreement, by and between Anestel and R & D Circuits, dated May 2009.

9. Software License Agreement, dated December 18, 2003, between Cimnet Systems, Inc. and R & D Circuits.

10. Agreement on Licenses dated as of September 22, 2011 by and between Cascade Microtech, Inc. and R&D Sockets.